

SANYO Semiconductors

DATA SHEET

An ON Semiconductor Company

N-Channel Silicon MOSFET ECH8663R — General-Purpose Switching Device **Applications**

Best suited for LiB charging and discharging switch

· Built-in gate protection resistor

Halogen free compliance

Features

- · Low ON-resistance
- 2.5V drive
- Common-drain type
- Protection diode in

Specifications

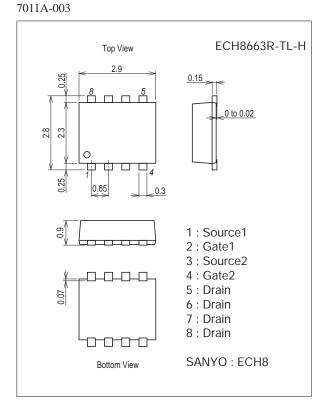
Absolute Maximum Ratings at Ta=25°C

-				
Parameter	Symbol	Conditions	Ratings	Unit
Drain-to-Source Voltage	VDSS		30	V
Gate-to-Source Voltage	VGSS		±12	V
Drain Current (DC)	ID		8	А
Drain Current (Pulse)	IDP	PW≤10µs, duty cycle≤1%	60	А
Allowable Power Dissipation	PD	When mounted on ceramic substrate (900mm ² ×0.8mm) 1unit	1.4	W
Total Power Dissipation	PT	When mounted on ceramic substrate (900mm ² ×0.8mm)	1.5	W
Channel Temperature	Tch		150	°C
Storage Temperature	Tstg		-55 to +150	°C

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Package Dimensions

unit : mm (typ)

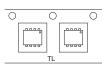


Product & Package Information

- · Package : ECH8
- JEITA, JEDEC
- Minimum Packing Quantity : 3,000 pcs./reel

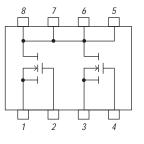
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Packing Type : TL



Marking ΤJ LOT No. П

Electrical Connection

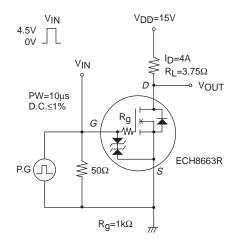


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Electrical Characteristics at Ta=25°C

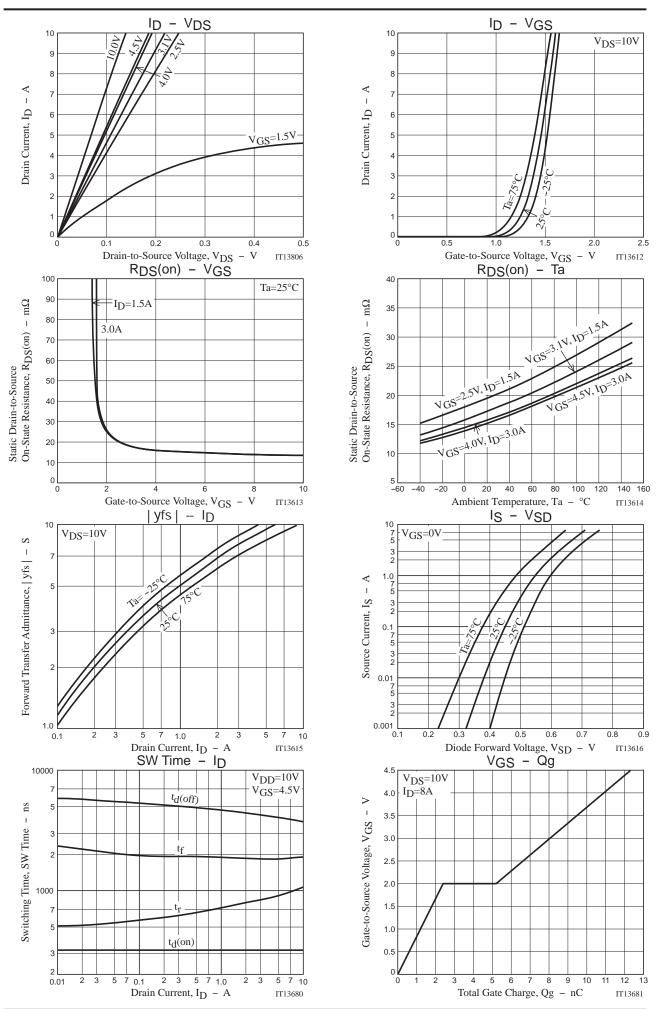
Devenue	Cumphial		Ratings				
Parameter	Symbol	Conditions	min	typ	max	Unit	
Drain-to-Source Breakdown Voltage	V(BR)DSS	ID=1mA, VGS=0V	30			V	
Zero-Gate Voltage Drain Current	IDSS	V _{DS} =30V, V _{GS} =0V			1	μΑ	
Gate-to-Source Leakage Current	IGSS	V _{GS} =±8V, V _{DS} =0V			±10	μΑ	
Cutoff Voltage	V _{GS} (off)	V _{DS} =10V, I _D =1mA	0.5		1.3	V	
Forward Transfer Admittance	ard Transfer Admittance yfs VDS=1		5	8.5		S	
	R _{DS} (on)1	ID=4A, VGS=4.5V	10.5	15.5	20.5	mΩ	
Statia Drain to Source On State Decistance	R _{DS} (on)2	ID=4A, VGS=4.0V	11	16	21	mΩ	
Static Drain-to-Source On-State Resistance	R _{DS} (on)3	ID=2A, VGS=3.1V	12	17.5	23	mΩ	
	RDS(on)4	ID=2A, VGS=2.5V	12	20	28	mΩ	
Turn-ON Delay Time	t _d (on)			320		ns	
Rise Time	tr			850		ns	
Turn-OFF Delay Time	t _d (off)	See specified Test Circuit.		4200		ns	
Fall Time	tf	-		1800		ns	
Total Gate Charge	Qg			12.3		nC	
Gate-to-Source Charge	Qgs	V _{DS} =10V, V _{GS} =4.5V, I _D =8A		2.4		nC	
Gate-to-Drain "Miller" Charge	Qgd	1		2.8		nC	
Diode Forward Voltage	V _{SD}	IS=8A, VGS=0V	1	0.75	1.2	V	

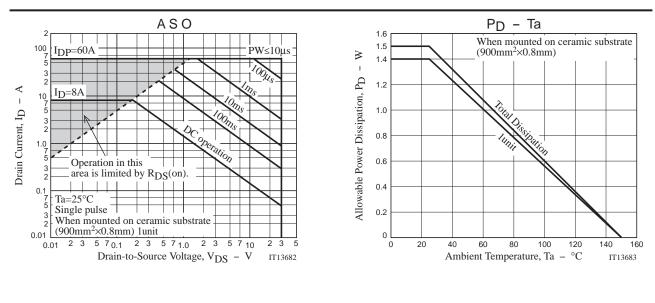
Switching Time Test Circuit



Ordering Information

3				
Device	Device Package		memo	
ECH8663R-TL-H	ECH8	3,000pcs./reel	Pb Free and Halogen Free	





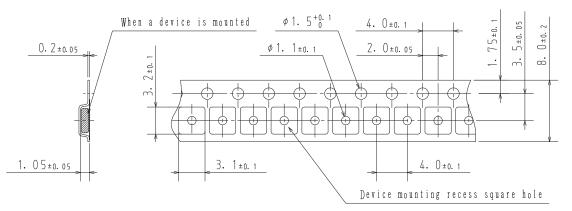
Embossed Taping Specification ECH8663R-TL-H

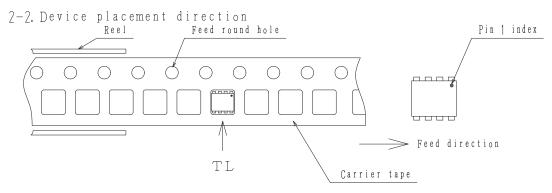
1. Packing Format

ECHO CFHO 3,000 70,000 70,000 1 Dimensions:mm (external) 183×72×185 Dimensions:mm (external) Packing method (unit:mm) Quartity Quantity Image: Comparison of a label 108 Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label	Package Name	Carrier Tape	Maximum Number of devices contained (pcs)			Packing format		
EVENTO CTTIC J, 000 J, 000 J, 000 J, 000 J, 000 Jimensions:mm (external) Jimensions:mm (external) Dimensions:mm (external) 183×72×185 440×195×210 Add over the state of the		Туре	Reel	Inner box	Outer box	Inner BOX $(C-1)$ Outer BOX $(A-7)$		
Dimensions:mm (external) Dimensions:mm (external) 183×72×185 440×195×210 Add Ox 195×210 440×195×210 Packing method (unit:mm) Packing method Outer box label (unit:mm) Image: Construction of a label and change in physical distribution process. Image: Construction of a label and change in physical distribution process. Image: Construction of a label and change in physical distribution process. Image: Construction of a label and change in physical distribution process. Image: Construction of a label and change in physical distribution process. Image: Construction of a label and change in physical distribution process. Image: Construction of a label and change in physical distribution process. Image: Construction of a label and change in physical distribution process. Image: Construction of a label and change in physical distribution process. Image: Construction of a label and change in physical distribution process. Image: Construction of a label and change in physical distribution process. Image: Construction of a label and change in physical distribution process. Image: Construction of a label and physical distribution process. Image: Construction of a label and physical distribution process. Image: Construction of a label and physical distribution process.	ECH8	CPH6	3,000	15,000	90,000	5 reels contained 6 inner boxes contained		
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Packing method (unit:mm) It is a label at the time of factory shipme The form of a label may change in physical distribution process. Type No. 69 LOT No. (Unit:minimum minimum mini						183×72×185 440×195×210		
treatment of the terminal is lead free. Label JEITA Phase LEAD FREE 3 JEITA Phase 3A	Packing met	Type LOT Quan Orig	No. tity in	-> (P. -> (P. -> (Q. ->	(u: TYPE 0000C IIIIIIIIIIIIIIIIIIIIIIIIIIIIIIIII	nner box label Outer box label nit:mm) Tis a label at the time of factory shipments. The form of a label may change in physical distribution process. 108 000000 TYPE CODE 000000 ************************************		

2. Taping configuration

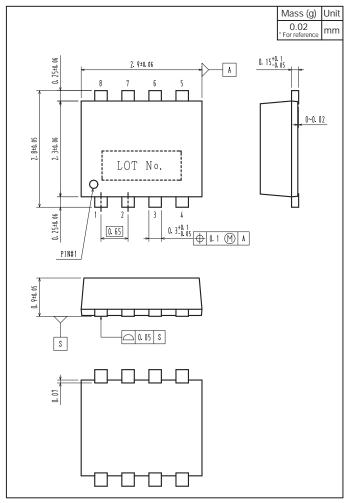
2-1. Carrier tape size (unit:mm)



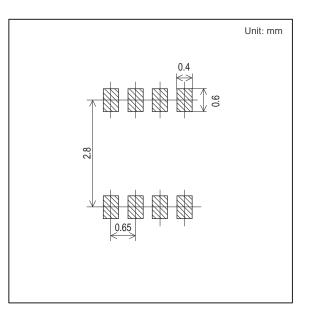


Those with pin 1 index on the feed hole side ·····TL

Outline Drawing ECH8663R-TL-H



Land Pattern Example



Note on usage : Since the ECH8663R is a MOSFET product, please avoid using this device in the vicinity of highly charged objects.

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